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Hermes European Embedded Die Consortia Selects FlipChip International's EDC TM (Embeddable Die Customization (TM)) Technology

PHOENIX, ARIZONA, July 8, 2008 - Hermes, the European consortia for the development and industrialization of embedded die technology has announced FlipChip International, LLC as an associate partner. Following the successful launch of FlipChip International's EDC TM (Embeddable Die Customization TM) technology in November, 2007, Hermes has decided to leverage this capability to enable realization of a solution for heterogeneous systems integration.

The Hermes Consortia, launched on May 1, 2008 (coordinated by AT&S of Leoben, Austria, one of the leading PCB manufacturers worldwide) aims to bring together complimentary partners from the Printed Circuit Board, Wafer Level Processing and Test Industries in order to enable the infrastructure for embedded die technology in the Integrated Device Manufacturers (IDM) and OEM markets. Hermes, will stimulate a market pull by forming an industrial potential that is willing to industrialize chip embedding technology and drive the technology by an open architecture.

The versatility of FCI's EDC (TM) technology supports the integration of most device technologies into emerging embedded die packaging schemes like those being developed within the Hermes consortia. The availability of FCI's EDC (TM) technology with available thin film redistribution options provides a standardized die preparation format for Hermes' embedded die needs.

Ted Tessier, Chief Technical Officer of FlipChip International, said "FCI is very pleased to have had the opportunity to support the European Union's Hiding Dies program in the past and look forward to supporting the follow-on Hermes project. FCI's EDC (TM) technology offering is targeted at providing part of the infrastructure needed to support the migration of embedded die technologies from development through to high volume adoption in portable handheld and other products."

Hannes Stahr, Manager R&D technology implementation, of AT&S, said: "Hermes is the European answer to the active embedding activities in far east. We see supply chain management, standardization of components, design, and testing as the most critical topics that have to be solved in order to provide for a successful industrialization. FCI will play an important role in supporting Hermes and for the project's overall success".

FlipChip International, LLC is a privately-held supplier of wafer bumping, wafer level processing and post passivation processes, products, services and solutions to the semiconductor industry. FlipChip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for the semiconductor and renewable energy markets.

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